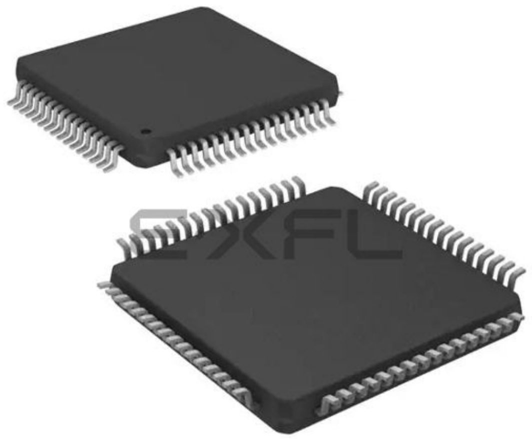

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	32KB (16K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	902 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c756a-16i-pt

TABLE 1-1: PIC17CXXX FAMILY OF DEVICES

Features		PIC17C42A	PIC17C43	PIC17C44	PIC17C752	PIC17C756A	PIC17C762	PIC17C766
Maximum Frequency of Operation		33 MHz	33 MHz	33 MHz	33 MHz	33 MHz	33 MHz	33 MHz
Operating Voltage Range		2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V	3.0 - 5.5V	3.0 - 5.5V	3.0 - 5.5V	3.0 - 5.5V
Program Memory (x16)	(EPROM)	2 K	4 K	8 K	8 K	16 K	8 K	16 K
	(ROM)	—	—	—	—	—	—	—
Data Memory (bytes)		232	454	454	678	902	678	902
Hardware Multiplier (8 x 8)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer0 (16-bit + 8-bit postscaler)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer1 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer2 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer3 (16-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Capture inputs (16-bit)		2	2	2	4	4	4	4
PWM outputs (up to 10-bit)		2	2	2	3	3	3	3
USART/SCI		1	1	1	2	2	2	2
A/D channels (10-bit)		—	—	—	12	12	16	16
SSP (SPI/I^{2}C w/Master mode)		—	—	—	Yes	Yes	Yes	Yes
Power-on Reset		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Watchdog Timer		Yes	Yes	Yes	Yes	Yes	Yes	Yes
External Interrupts		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Interrupt Sources		11	11	11	18	18	18	18
Code Protect		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Brown-out Reset		—	—	—	Yes	Yes	Yes	Yes
In-Circuit Serial Programming		—	—	—	Yes	Yes	Yes	Yes
I/O Pins		33	33	33	50	50	66	66
I/O High Current Capability	Source	25 mA	25 mA	25 mA	25 mA	25 mA	25 mA	25 mA
	Sink	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)
Package Types		40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	64-pin TQFP 68-pin PLCC	64-pin TQFP 68-pin PLCC	80-pin TQFP 84-pin PLCC	80-pin TQFP 84-pin PLCC

Note 1: Pins RA2 and RA3 can sink up to 60 mA.

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC17CXXX can be attributed to a number of architectural features, commonly found in RISC microprocessors. To begin with, the PIC17CXXX uses a modified Harvard architecture. This architecture has the program and data accessed from separate memories. So, the device has a program memory bus and a data memory bus. This improves bandwidth over traditional von Neumann architecture, where program and data are fetched from the same memory (accesses over the same bus). Separating program and data memory further allows instructions to be sized differently than the 8-bit wide data word. PIC17CXXX opcodes are 16-bits wide, enabling single word instructions. The full 16-bit wide program memory bus fetches a 16-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions. Consequently, all instructions execute in a single cycle (121 ns @ 33 MHz), except for program branches and two special instructions that transfer data between program and data memory.

The PIC17CXXX can address up to 64K x 16 of program memory space.

The **PIC17C752** and **PIC17C762** integrate 8K x 16 of EPROM program memory on-chip.

The **PIC17C756A** and **PIC17C766** integrate 16K x 16 EPROM program memory on-chip.

A simplified block diagram is shown in Figure 3-1. The descriptions of the device pins are listed in Table 3-1.

Program execution can be internal only (Microcontroller or Protected Microcontroller mode), external only (Microprocessor mode), or both (Extended Microcontroller mode). Extended Microcontroller mode does not allow code protection.

The PIC17CXXX can directly or indirectly address its register files or data memory. All special function registers, including the Program Counter (PC) and Working Register (WREG), are mapped in data memory. The PIC17CXXX has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC17CXXX simple, yet efficient. In addition, the learning curve is reduced significantly.

One of the PIC17CXXX family architectural enhancements from the PIC16CXX family, allows two file registers to be used in some two operand instructions. This allows data to be moved directly between two registers without going through the WREG register, thus increasing performance and decreasing program memory usage.

The PIC17CXXX devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The WREG register is an 8-bit working register used for ALU operations.

All PIC17CXXX devices have an 8 x 8 hardware multiplier. This multiplier generates a 16-bit result in a single cycle.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), Zero (Z) and Overflow (OV) bits in the ALUSTA register. The C and DC bits operate as a $\overline{\text{borrow}}$ and $\overline{\text{digit borrow}}$ out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

Signed arithmetic is comprised of a magnitude and a sign bit. The overflow bit indicates if the magnitude overflows and causes the sign bit to change state. That is, if the result of 8-bit signed operations is greater than 127 (7Fh), or less than -128 (80h).

Signed math can have greater than 7-bit values (magnitude), if more than one byte is used. The overflow bit only operates on bit6 (MSb of magnitude) and bit7 (sign bit) of each byte value in the ALU. That is, the overflow bit is not useful if trying to implement signed math where the magnitude, for example, is 11-bits.

If the signed math values are greater than 7-bits (such as 15-, 24-, or 31-bit), the algorithm must ensure that the low order bytes of the signed value ignore the overflow status bit.

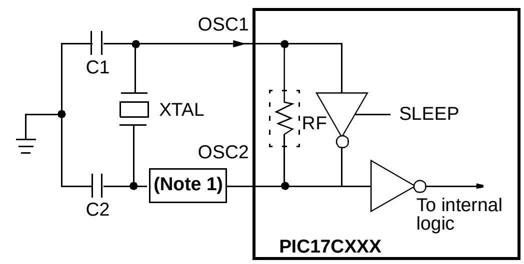
Example 3-1 shows two cases of doing signed arithmetic. The Carry (C) bit and the Overflow (OV) bit are the most important status bits for signed math operations.

EXAMPLE 3-1: 8-BIT MATH ADDITION

Hex Value	Signed Values	Unsigned Values
FFh	-1	255
+ 01h	+ 1	+ 1
= 00h	= 0 (FEh)	= 256 → 00h
C bit = 1	C bit = 1	C bit = 1
OV bit = 0	OV bit = 0	OV bit = 0
DC bit = 1	DC bit = 1	DC bit = 1
Z bit = 1	Z bit = 1	Z bit = 1

Hex Value	Signed Values	Unsigned Values
7Fh	127	127
+ 01h	+ 1	+ 1
= 80h	= 128 → 00h	= 128
C bit = 0	C bit = 0	C bit = 0
OV bit = 1	OV bit = 1	OV bit = 1
DC bit = 1	DC bit = 1	DC bit = 1
Z bit = 0	Z bit = 0	Z bit = 0

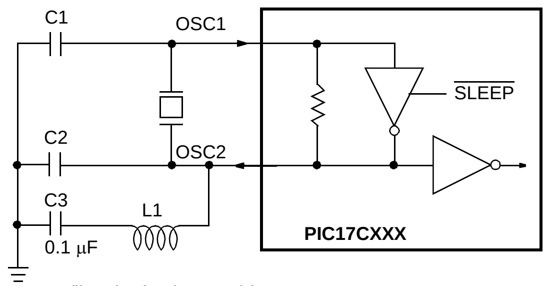
FIGURE 4-2: CRYSTAL OR CERAMIC RESONATOR OPERATION (XT OR LF OSC CONFIGURATION)



See Table 4-1 and Table 4-2 for recommended values of C1 and C2.

Note 1: A series resistor (Rs) may be required for AT strip cut crystals.

FIGURE 4-3: CRYSTAL OPERATION, OVERTONE CRYSTALS (XT OSC CONFIGURATION)



To filter the fundamental frequency:

$$\frac{1}{L1 * C2} = (2\pi f)^2$$

Where f = tank circuit resonant frequency. This should be midway between the fundamental and the 3rd overtone frequencies of the crystal.
C3 blocks DC current to ground.

TABLE 4-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Oscillator Type	Resonator Frequency	Capacitor Range C1 = C2(1)
LF	455 kHz 2.0 MHz	15 - 68 pF 10 - 33 pF
XT	4.0 MHz 8.0 MHz 16.0 MHz	22 - 68 pF 33 - 100 pF 33 - 100 pF

Higher capacitance increases the stability of the oscillator, but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

Note 1: These values include all board capacitances on this pin. Actual capacitor value depends on board capacitance.

Resonators Used:

455 kHz	Panasonic EFO-A455K04B	± 0.3%
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%

Resonators used did not have built-in capacitors.

TABLE 4-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Freq	C1(2)	C2(2)
LF	32 kHz 1 MHz 2 MHz	100-150 pF 10-68 pF 10-68 pF	100-150 pF 10-68 pF 10-68 pF
XT	2 MHz 4 MHz 8 MHz 16 MHz 24 MHz(1) 32 MHz(1)	47-100 pF 15-68 pF 15-47 pF 15-47 pF 15-47 pF 10-47 pF	47-100 pF 15-68 pF 15-47 pF 15-47 pF 15-47 pF 10-47 pF

Higher capacitance increases the stability of the oscillator, but also increases the start-up time and the oscillator current. These values are for design guidance only. Rs may be required in XT mode to avoid overdriving the crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values for external components.

Note 1: Overtone crystals are used at 24 MHz and higher. The circuit in Figure 4-3 should be used to select the desired harmonic frequency.

2: These values include all board capacitances on this pin. Actual capacitor value depends on board capacitance.

Crystals Used:

32.768 kHz	Epson C-001R32.768K-A	± 20 PPM
1.0 MHz	ECS-10-13-1	± 50 PPM
2.0 MHz	ECS-20-20-1	± 50 PPM
4.0 MHz	ECS-40-20-1	± 50 PPM
8.0 MHz	ECS ECS-80-S-4 ECS-80-18-1	± 50 PPM
16.0 MHz	ECS-160-20-1	± 50 PPM
25 MHz	CTS CTS25M	± 50 PPM
32 MHz	CRYSTEK HF-2	± 50 PPM

15.1 SPI Mode

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. All four modes of SPI are supported. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO)
- Serial Data In (SDI)
- Serial Clock (SCK)

Additionally, a fourth pin may be used when in a Slave mode of operation:

- Slave Select ($\overline{SS}$)

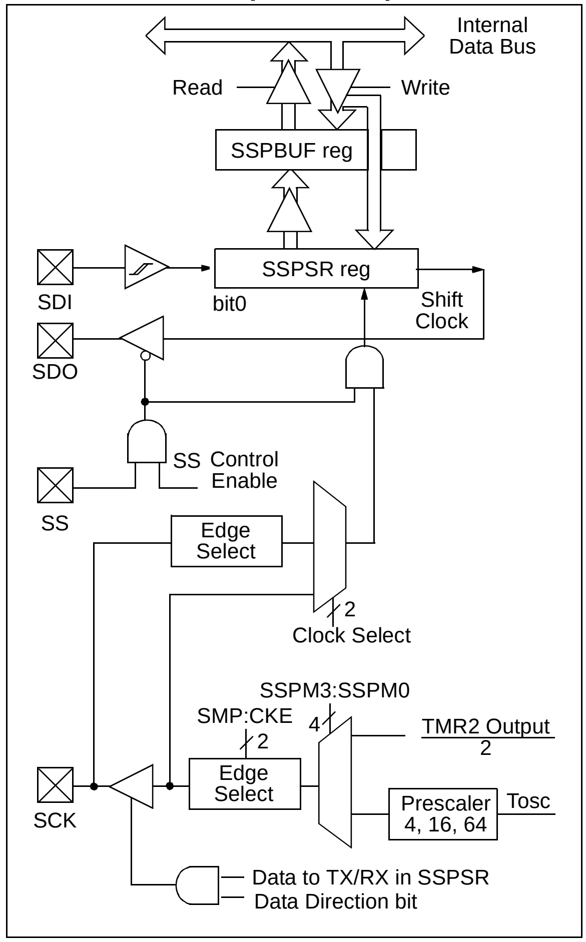
15.1.1 OPERATION

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON1 register (SSPCON1<5:0>) and SSPSTAT<7:6>. These control bits allow the following to be specified:

- Master mode (SCK is the clock output)
- Slave mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Data Input Sample Phase (middle or end of data output time)
- Clock Edge (output data on rising/falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select mode (Slave mode only)

Figure 15-4 shows the block diagram of the MSSP module when in SPI mode.

FIGURE 15-4: MSSP BLOCK DIAGRAM (SPI MODE)



The MSSP consists of a transmit/receive Shift Register (SSPSR) and a Buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR, until the received data is ready. Once the 8-bits of data have been received, that byte is moved to the SSPBUF register. Then the buffer full detect bit BF (SSPSTAT<0>) and the interrupt flag bit SSPIF (PIR2<7>) are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit WCOL (SSPCON1<7>) will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully.

15.2.3 SLEEP OPERATION

While in SLEEP mode, the I^2C module can receive addresses or data and when an address match or complete byte transfer occurs, wake the processor from SLEEP (if the SSP interrupt is enabled).

15.2.4 EFFECTS OF A RESET

A RESET disables the SSP module and terminates the current transfer.

TABLE 15-3: REGISTERS ASSOCIATED WITH I^2C OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	POR, BOR	$\overline{MCLR}$, WDT
07h, Unbanked	INTSTA	PEIF	T0CKIF	T0IF	INTF	PEIE	T0CKIE	T0IE	INTE	0000 0000	0000 0000
10h, Bank 4	PIR2	SSPIF	BCLIF	ADIF	—	CA4IF	CA3IF	TX2IF	RC2IF	000- 0000	000- 0000
11h, Bank 4	PIE2	SSPIE	BCLIE	ADIE	—	CA4IE	CA3IE	TX2IE	RC2IE	000- 0000	000- 0000
10h. Bank 6	SSPADD	Synchronous Serial Port (I^2C mode) Address Register								0000 0000	0000 0000
14h, Bank 6	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
11h, Bank 6	SSPCON1	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
12h, Bank 6	SSPCON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000	0000 0000
13h, Bank 6	SSPSTAT	SMP	CKE	$D/\overline{A}$	P	S	$R/\overline{W}$	UA	BF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the SSP in I^2C mode.

The ADRESH:ADRESL registers contain the 10-bit result of the A/D conversion. When the A/D conversion is complete, the result is loaded into this A/D result register pair, the GO/$\overline{\text{DONE}}$ bit (ADCON0<2>) is cleared and A/D interrupt flag bit, ADIF is set. The block diagrams of the A/D module are shown in Figure 16-1.

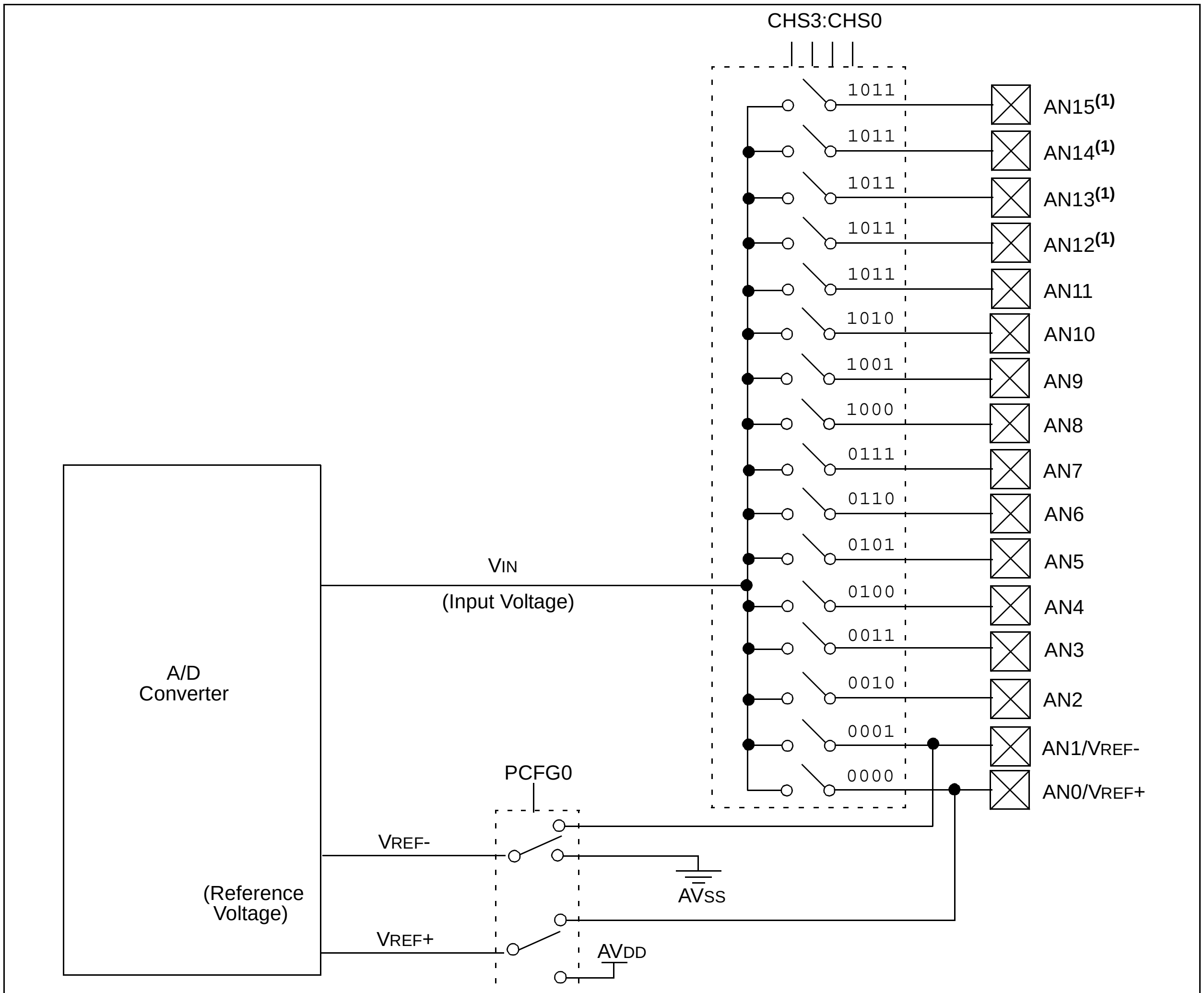
After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding DDR bits selected as inputs. To determine sample time, see Section 16.1. After this acquisition time has elapsed, the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

1. Configure the A/D module:
   a) Configure analog pins/voltage reference/ and digital I/O (ADCON1)
   b) Select A/D input channel (ADCON0)
   c) Select A/D conversion clock (ADCON0)
   d) Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   a) Clear ADIF bit
   b) Set ADIE bit
   c) Clear GLINTD bit
3. Wait the required acquisition time.
4. Start conversion:
   a) Set GO/$\overline{\text{DONE}}$ bit (ADCON0)
5. Wait for A/D conversion to complete, by either:
   a) Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared

   OR

   b) Waiting for the A/D interrupt
6. Read A/D Result register pair (ADRESH:ADRESL), clear bit ADIF, if required.
7. For next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2TAD is required before next acquisition starts.

FIGURE 16-1: A/D BLOCK DIAGRAM



Note 1: These channels are only available on PIC16C76X devices.

16.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as T_{AD}. The A/D conversion requires a minimum $12T_{AD}$ per 10-bit conversion. The source of the A/D conversion clock is software selected. The four possible options for T_{AD} are:

- $8T_{OSC}$
- $32T_{OSC}$
- $64T_{OSC}$
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (T_{AD}) must be selected to ensure a minimum T_{AD} time of 1.6 μs.

Table 16-1 and Table 16-2 show the resultant T_{AD} times derived from the device operating frequencies and the A/D clock source selected. These times are for standard voltage range devices.

TABLE 16-1: T_{AD} vs. DEVICE OPERATING FREQUENCIES (STANDARD DEVICES (C))

AD Clock Source (T_{AD})		Max F_{OSC} (MHz)
Operation	**ADCS1:ADCS0**	
$8T_{OSC}$	`00`	5
$32T_{OSC}$	`01`	20
$64T_{OSC}$	`10`	33
RC	`11`	—

Note: When the device frequency is greater than 1 MHz, the RC A/D conversion clock source is only recommended for SLEEP operation.

TABLE 16-2: T_{AD} vs. DEVICE OPERATING FREQUENCIES (EXTENDED VOLTAGE DEVICES (LC))

AD Clock Source (T_{AD})		Max F_{OSC} (MHz)
Operation	**ADCS1:ADCS0**	
$8T_{OSC}$	`00`	2.67
$32T_{OSC}$	`01`	10.67
$64T_{OSC}$	`10`	21.33
RC	`11`	—

Note: When the device frequency is greater than 1 MHz, the RC A/D conversion clock source is only recommended for SLEEP operation.

16.7 A/D Accuracy/Error

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, T_{AD} should be derived from the device oscillator.

The absolute accuracy specified for the A/D converter includes the sum of all contributions for quantization error, integral error, differential error, full scale error, offset error, and monotonicity. It is defined as the maximum deviation from an actual transition versus an ideal transition for any code. The absolute error of the A/D converter is specified at < ±1 LSb for $V_{DD} = V_{REF}$ (over the device's specified operating range). However, the accuracy of the A/D converter will degrade as V_{REF} diverges from V_{DD}.

For a given range of analog inputs, the output digital code will be the same. This is due to the quantization of the analog input to a digital code. Quantization error is typically ± 1/2 LSb and is inherent in the analog to digital conversion process. The only way to reduce quantization error is to increase the resolution of the A/D converter or oversample.

Offset error measures the first actual transition of a code versus the first ideal transition of a code. Offset error shifts the entire transfer function. Offset error can be calibrated out of a system or introduced into a system through the interaction of the total leakage current and source impedance at the analog input.

Gain error measures the maximum deviation of the last actual transition and the last ideal transition adjusted for offset error. This error appears as a change in slope of the transfer function. The difference in gain error to full scale error is that full scale does not take offset error into account. Gain error can be calibrated out in software.

Linearity error refers to the uniformity of the code changes. Linearity errors cannot be calibrated out of the system. Integral non-linearity error measures the actual code transition versus the ideal code transition, adjusted by the gain error for each code.

Differential non-linearity measures the maximum actual code width versus the ideal code width. This measure is unadjusted.

The maximum pin leakage current is specified in the Device Data Sheet electrical specification (Table 20-2, parameter #D060).

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, T_{AD} should be derived from the device oscillator. T_{AD} must not violate the minimum and should be minimized to reduce inaccuracies due to noise and sampling capacitor bleed off.

In systems where the device will enter SLEEP mode after the start of the A/D conversion, the RC clock source selection is required. In this mode, the digital noise from the modules in SLEEP are stopped. This method gives high accuracy.

16.8 Connection Considerations

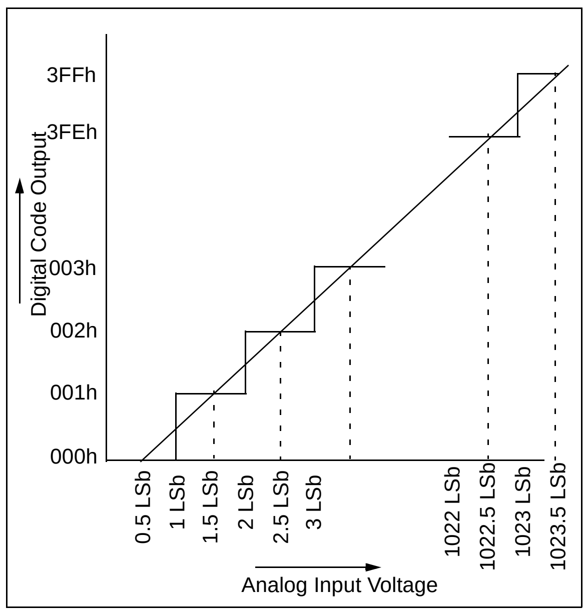
If the input voltage exceeds the rail values (V_{SS} or V_{DD}) by greater than 0.3V, then the accuracy of the conversion is out of specification.

An external RC filter is sometimes added for anti-aliasing of the input signal. The R component should be selected to ensure that the total source impedance is kept under the 10 kΩ recommended specification. Any external components connected (via hi-impedance) to an analog input pin (capacitor, zener diode, etc.) should have very little leakage current at the pin.

16.9 Transfer Function

The transfer function of the A/D converter is as follows: the first transition occurs when the analog input voltage (V_{AIN}) equals Analog V_{REF} / 1024 (Figure 16-7).

FIGURE 16-7: A/D TRANSFER FUNCTION



17.3 Watchdog Timer (WDT)

The Watchdog Timer's function is to recover from software malfunction, or to reset the device while in SLEEP mode. The WDT uses an internal free running on-chip RC oscillator for its clock source. This does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins has been stopped, for example, by execution of a `SLEEP` instruction. During normal operation, a WDT time-out generates a device RESET. The WDT can be permanently disabled by programming the configuration bits WDTPS1:WDTPS0 as '`00`' (Section 17.1).

Under normal operation, the WDT must be cleared on a regular interval. This time must be less than the minimum WDT overflow time. Not clearing the WDT in this time frame will cause the WDT to overflow and reset the device.

17.3.1 WDT PERIOD

The WDT has a nominal time-out period of 12 ms (with postscaler = 1). The time-out periods vary with temperature, V_{DD} and process variations from part to part (see DC specs). If longer time-out periods are desired, configuration bits should be used to enable the WDT with a greater prescale. Thus, typical time-out periods up to 3.0 seconds can be realized.

The `CLRWDT` and `SLEEP` instructions clear the WDT and its postscale setting and prevent it from timing out, thus generating a device RESET condition.

The $\overline{TO}$ bit in the CPUSTA register will be cleared upon a WDT time-out.

17.3.2 CLEARING THE WDT AND POSTSCALER

The WDT and postscaler are cleared when:

- The device is in the RESET state
- A `SLEEP` instruction is executed
- A `CLRWDT` instruction is executed
- Wake-up from SLEEP by an interrupt

The WDT counter/postscaler will start counting on the first edge after the device exits the RESET state.

17.3.3 WDT PROGRAMMING CONSIDERATIONS

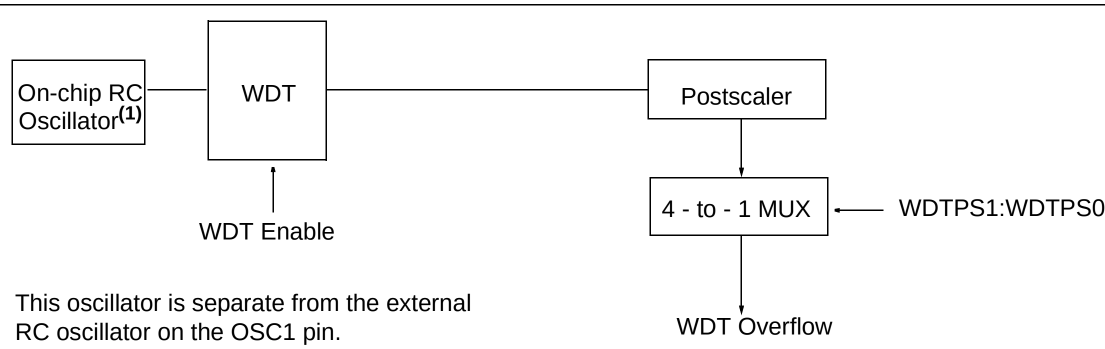
It should also be taken in account that under worst case conditions (V_{DD} = Min., Temperature = Max., Max. WDT postscaler), it may take several seconds before a WDT time-out occurs.

The WDT and postscaler become the Power-up Timer whenever the PWRT is invoked.

17.3.4 WDT AS NORMAL TIMER

When the WDT is selected as a normal timer, the clock source is the device clock. Neither the WDT nor the postscaler are directly readable or writable. The overflow time is 65536 T_{OSC} cycles. On overflow, the $\overline{TO}$ bit is cleared (device is not RESET). The `CLRWDT` instruction can be used to set the $\overline{TO}$ bit. This allows the WDT to be a simple overflow timer. The simple timer does not increment when in SLEEP.

FIGURE 17-1: WATCHDOG TIMER BLOCK DIAGRAM



Note 1: This oscillator is separate from the external RC oscillator on the OSC1 pin.

TABLE 17-2: REGISTERS/BITS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	$\overline{MCLR}$, WDT
—	Config	See Figure 17-1 for location of WDTPSx bits in Configuration Word.								(Note 1)	(Note 1)
06h, Unbanked	CPUSTA	—	—	STKAV	GLINTD	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	`--11 11qq`	`--11 qquu`

Legend: - = unimplemented, read as '0', `q` = value depends on condition. Shaded cells are not used by the WDT.
Note 1: This value will be as the device was programmed, or if unprogrammed, will read as all '1's.

17.4 Power-down Mode (SLEEP)

The Power-down mode is entered by executing a `SLEEP` instruction. This clears the Watchdog Timer and postscaler (if enabled). The $\overline{PD}$ bit is cleared and the $\overline{TO}$ bit is set (in the CPUSTA register). In SLEEP mode, the oscillator driver is turned off. The I/O ports maintain their status (driving high,low, or hi-impedance input).

The $\overline{MCLR}$/VPP pin must be at a logic high level (VIHMC). A WDT time-out RESET does not drive the $\overline{MCLR}$/VPP pin low.

17.4.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

- Power-on Reset
- Brown-out Reset
- External RESET input on $\overline{MCLR}$/VPP pin
- WDT Reset (if WDT was enabled)
- Interrupt from RA0/INT pin, RB port change, T0CKI interrupt, or some peripheral interrupts

The following peripheral interrupts can wake the device from SLEEP:

- Capture interrupts
- USART synchronous slave transmit interrupts
- USART synchronous slave receive interrupts
- A/D conversion complete
- SPI slave transmit/receive complete
- I^2C slave receive

Other peripherals cannot generate interrupts since during SLEEP, no on-chip Q clocks are present.

Any RESET event will cause a device RESET. Any interrupt event is considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the CPUSTA register can be used to determine the cause of a device RESET. The $\overline{PD}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The $\overline{TO}$ bit is cleared if WDT time-out occurred (and caused a RESET).

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GLINTD bit. If the GLINTD bit is set (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the GLINTD bit is clear (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt vector address. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

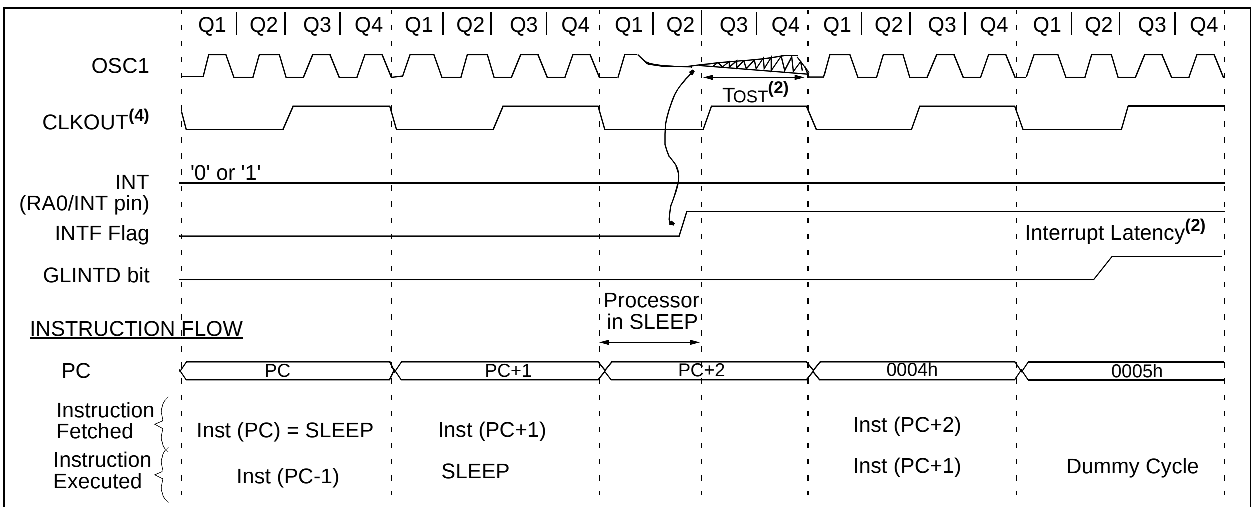
Note:	If the global interrupt is disabled (GLINTD is set), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bit set, the device will immediately wake-up from SLEEP. The $\overline{TO}$ bit is set and the $\overline{PD}$ bit is cleared.

The WDT is cleared when the device wakes from SLEEP, regardless of the source of wake-up.

17.4.1.1 Wake-up Delay

When the oscillator type is configured in XT or LF mode, the Oscillator Start-up Timer (OST) is activated on wake-up. The OST will keep the device in RESET for 1024TOSC. This needs to be taken into account when considering the interrupt response time when coming out of SLEEP.

FIGURE 17-2: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT or LF oscillator mode assumed.
2: TOST = 1024TOSC (drawing not to scale). This delay will not be there for RC osc mode.
3: When GLINTD = 0, processor jumps to interrupt routine after wake-up. If GLINTD = 1, execution will continue in line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

18.0 INSTRUCTION SET SUMMARY

The PIC17CXXX instruction set consists of 58 instructions. Each instruction is a 16-bit word divided into an OPCODE and one or more operands. The opcode specifies the instruction type, while the operand(s) further specify the operation of the instruction. The PIC17CXXX instruction set can be grouped into three types:

- byte-oriented
- bit-oriented
- literal and control operations

These formats are shown in Figure 18-1.

Table 18-1 shows the field descriptions for the opcodes. These descriptions are useful for understanding the opcodes in Table 18-2 and in each specific instruction descriptions.

For **byte-oriented instructions**, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' = '0', the result is placed in the WREG register. If 'd' = '1', the result is placed in the file register specified by the instruction.

For **bit-oriented instructions**, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control operations**, 'k' represents an 8- or 13-bit constant or literal value.

The instruction set is highly orthogonal and is grouped into:

- byte-oriented operations
- bit-oriented operations
- literal and control operations

All instructions are executed within one single instruction cycle, unless:

- a conditional test is true
- the program counter is changed as a result of an instruction
- a table read or a table write instruction is executed (in this case, the execution takes two instruction cycles with the second cycle executed as a NOP)

One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 25 MHz, the normal instruction execution time is 160 ns. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 320 ns.

TABLE 18-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (00h to FFh)
p	Peripheral register file address (00h to 1Fh)
i	Table pointer control i = '0' (do not change) i = '1' (increment after instruction execution)
t	Table byte select t = '0' (perform operation on lower byte) t = '1' (perform operation on upper byte literal field, constant data)
WREG	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= '0' or '1') The assembler will generate code with x = '0'. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select 0 = store result in WREG 1 = store result in file register f Default is d = '1'
u	Unused, encoded as '0'
s	Destination select 0 = store result in file register f and in the WREG 1 = store result in file register f Default is s = '1'
label	Label name
C,DC, Z,OV	ALU status bits Carry, Digit Carry, Zero, Overflow
GLINTD	Global Interrupt Disable bit (CPUSTA<4>)
TBLPTR	Table Pointer (16-bit)
TBLAT	Table Latch (16-bit) consists of high byte (TBLATH) and low byte (TBLATL)
TBLATL	Table Latch low byte
TBLATH	Table Latch high byte
TOS	Top-of-Stack
PC	Program Counter
BSR	Bank Select Register
WDT	Watchdog Timer Counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit
dest	Destination either the WREG register or the specified register file location
[ ]	Options
( )	Contents
$\rightarrow$	Assigned to
< >	Register bit field
$\in$	In the set of
italics	User defined term (font is courier)

CPFSLT — Compare f with WREG, skip if f < WREG

Syntax: [*label*] CPFSLT f

Operands: $0 \le f \le 255$

Operation: (f) – (WREG),
skip if (f) < (WREG)
(unsigned comparison)

Status Affected: None

Encoding:

0011	0000	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of WREG by performing an unsigned subtraction.

If the contents of 'f' are less than the contents of WREG, then the fetched instruction is discarded and a `NOP` is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1 (2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

Example:

```
HERE    CPFSLT REG
NLESS   :
LESS    :
```

Before Instruction
PC = Address (`HERE`)
W = ?

After Instruction
If REG < WREG;
PC = Address (`LESS`)
If REG ≥ WREG;
PC = Address (`NLESS`)

DAW — Decimal Adjust WREG Register

Syntax: [*label*] DAW f,s

Operands: $0 \le f \le 255$
$s \in [0,1]$

Operation: If [[WREG<7:4> > 9].OR.[C = 1]].AND.
[WREG<3:0> > 9]
then
WREG<7:4> + 7→ f<7:4>, s<7:4>;

If [WREG<7:4> > 9].OR.[C = 1]
then
WREG<7:4> + 6→ f<7:4>, s<7:4>;
else
WREG<7:4>→ f<7:4>, s<7:4>;

If [WREG<3:0> > 9].OR.[DC = 1]
then
WREG<3:0> + 6→ f<3:0>, s<3:0>;
else
WREG<3:0>→ f<3:0>, s<3:0>

Status Affected: C

Encoding:

0010	111s	ffff	ffff

Description: DAW adjusts the eight-bit value in WREG, resulting from the earlier addition of two variables (each in packed BCD format) and produces a correct packed BCD result.

s = 0: Result is placed in Data memory location 'f' and WREG.

s = 1: Result is placed in Data memory location 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f' and other specified register

Example: `DAW REG1, 0`

Before Instruction
WREG = 0xA5
REG1 = ??
C = 0
DC = 0

After Instruction
WREG = 0x05
REG1 = 0x05
C = 1
DC = 0

FIGURE 20-1: PIC17C7XX-33 VOLTAGE-FREQUENCY GRAPH

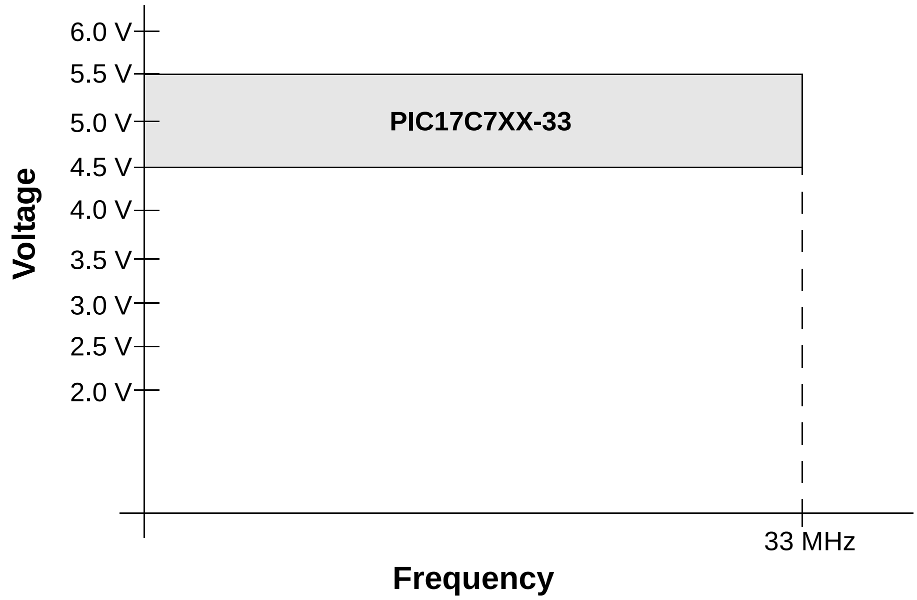


FIGURE 20-2: PIC17C7XX-16 VOLTAGE-FREQUENCY GRAPH

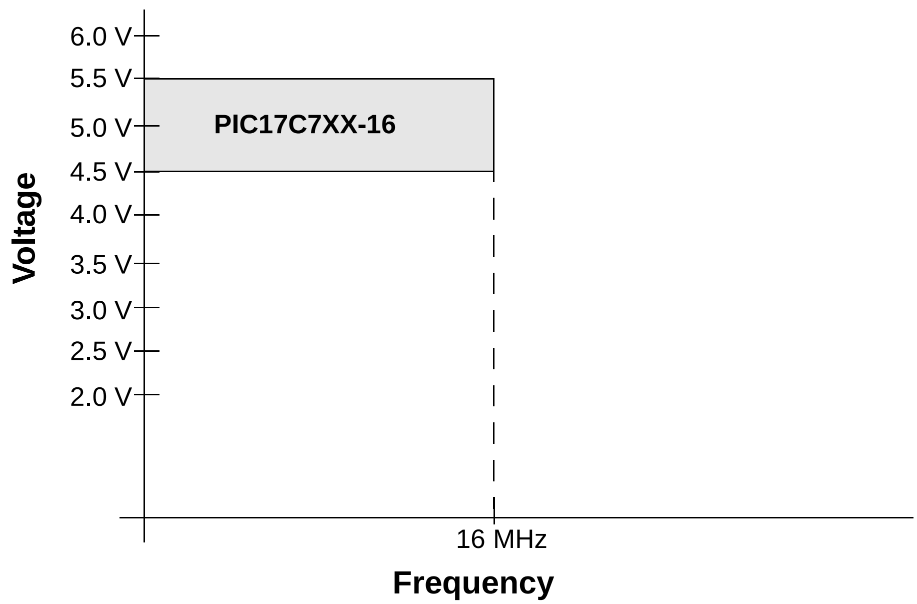
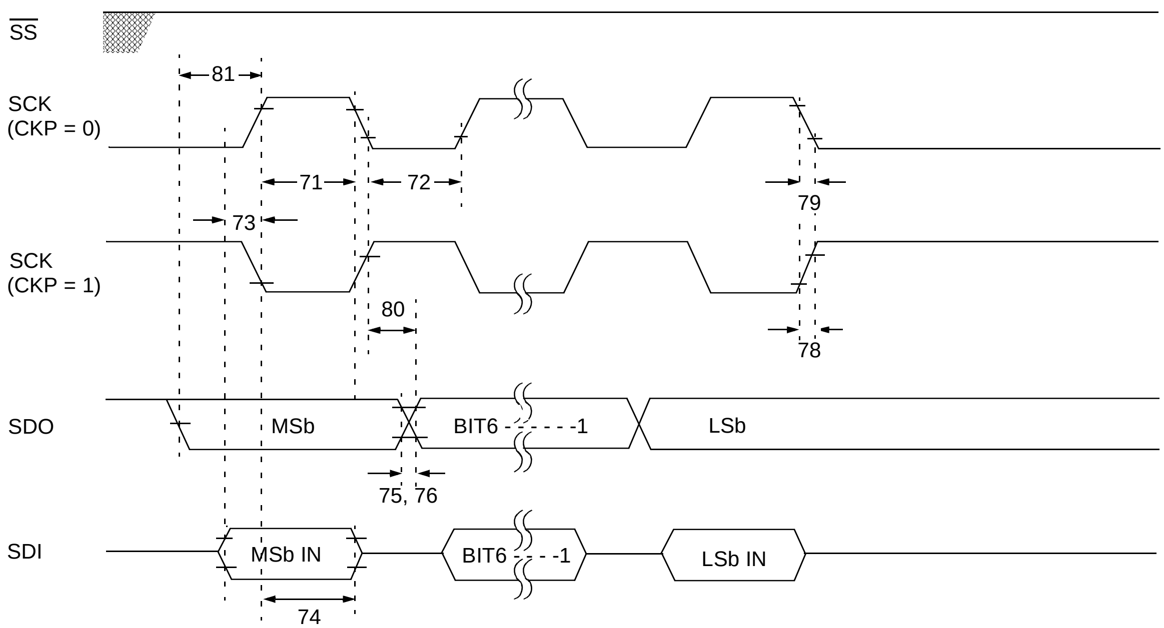


FIGURE 20-14: SPI MASTER MODE TIMING (CKE = 1)



Note: Refer to Figure 20-5 for load conditions.

TABLE 20-9: SPI MODE REQUIREMENTS (MASTER MODE, CKE = 1)

Param. No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
71	TscH	SCK input high time (Slave mode)	Continuous	1.25TCY + 30	—	—	ns	
71A			Single Byte	40	—	—	ns	**(Note 1)**
72	TscL	SCK input low time (Slave mode)	Continuous	1.25 TCY + 30	—	—	ns	
72A			Single Byte	40	—	—	ns	**(Note 1)**
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
73A	TB2B	Last clock edge of Byte1 to the 1st clock edge of Byte2		1.5TCY + 40	—	—	ns	**(Note 1)**
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
75	TdoR	SDO data output rise time		—	10	25	ns	
76	TdoF	SDO data output fall time		—	10	25	ns	
78	TscR	SCK output rise time (Master mode)		—	10	25	ns	
79	TscF	SCK output fall time (Master mode)		—	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge		—	—	50	ns	
81	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.
Note 1: Specification 73A is only required if specifications 71A and 72A are used.

FIGURE 20-25: MEMORY INTERFACE READ TIMING

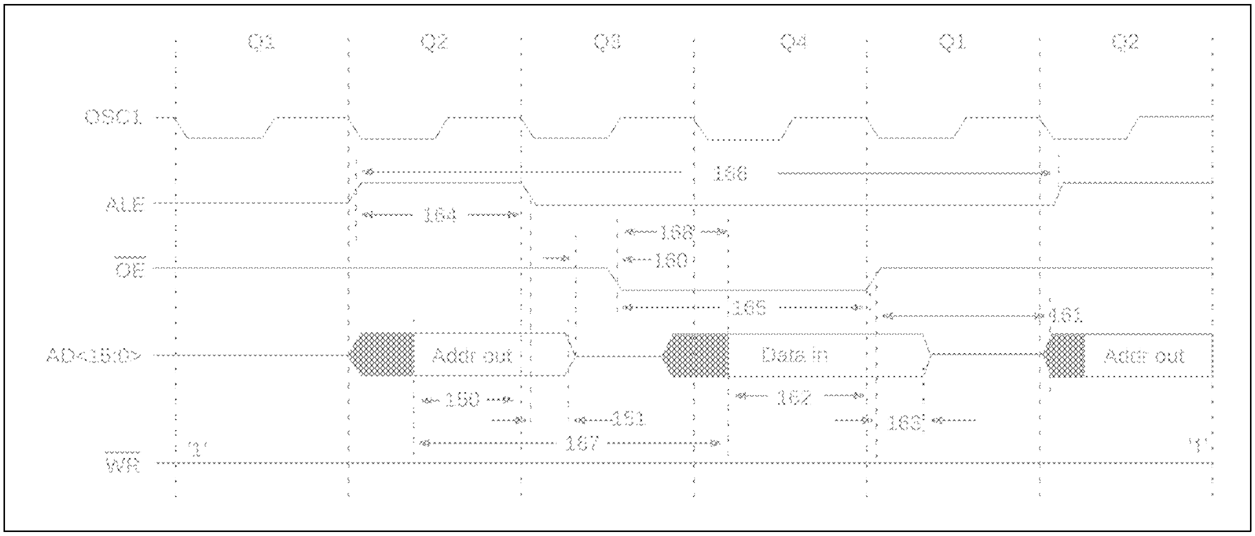


TABLE 20-21: MEMORY INTERFACE READ REQUIREMENTS

Param. No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD15:AD0 (address) valid to ALE↓ (address setup time)	PIC17**C**XXX	0.25TCY - 10	—	—	ns	
			PIC17**LC**XXX	0.25TCY - 10	—	—		
151	TalL2adI	ALE↓ to address out invalid (address hold time)	PIC17**C**XXX	5	—	—	ns	
			PIC17**LC**XXX	5	—	—		
160	TadZ2oeL	AD15:AD0 hi-impedance to $\overline{\text{OE}}$↓	PIC17**C**XXX	0	—	—	ns	
			PIC17**LC**XXX	0	—	—		
161	ToeH2adD	$\overline{\text{OE}}$↑ to AD15:AD0 driven	PIC17**C**XXX	0.25TCY - 15	—	—	ns	
			PIC17**LC**XXX	0.25TCY - 15	—	—		
162	TadV2oeH	Data in valid before $\overline{\text{OE}}$↑ (data setup time)	PIC17**C**XXX	35	—	—	ns	
			PIC17**LC**XXX	45	—	—		
163	ToeH2adI	$\overline{\text{OE}}$↑to data in invalid (data hold time)	PIC17**C**XXX	0	—	—	ns	
			PIC17**LC**XXX	0	—	—		
164	TalH	ALE pulse width	PIC17**C**XXX	—	0.25TCY	—	ns	
			PIC17**LC**XXX	—	0.25TCY	—		
165	ToeL	$\overline{\text{OE}}$ pulse width	PIC17**C**XXX	0.5TCY - 35	—	—	ns	
			PIC17**LC**XXX	0.5TCY - 35	—	—		
166	TalH2alH	ALE↑ to ALE↑(cycle time)	PIC17**C**XXX	—	TCY	—	ns	
			PIC17**LC**XXX	—	TCY	—		
167	Tacc	Address access time	PIC17**C**XXX	—	—	0.75TCY - 30	ns	
			PIC17**LC**XXX	—	—	0.75TCY - 45		
168	Toe	Output enable access time ($\overline{\text{OE}}$ low to data valid)	PIC17**C**XXX	—	—	0.5TCY - 45	ns	
			PIC17**LC**XXX	—	—	0.5TCY - 75		

† Data in “Typ” column is at 5V, 25°C unless otherwise stated.

FIGURE 21-7: TYPICAL IDD vs. FOSC OVER VDD (LF MODE)

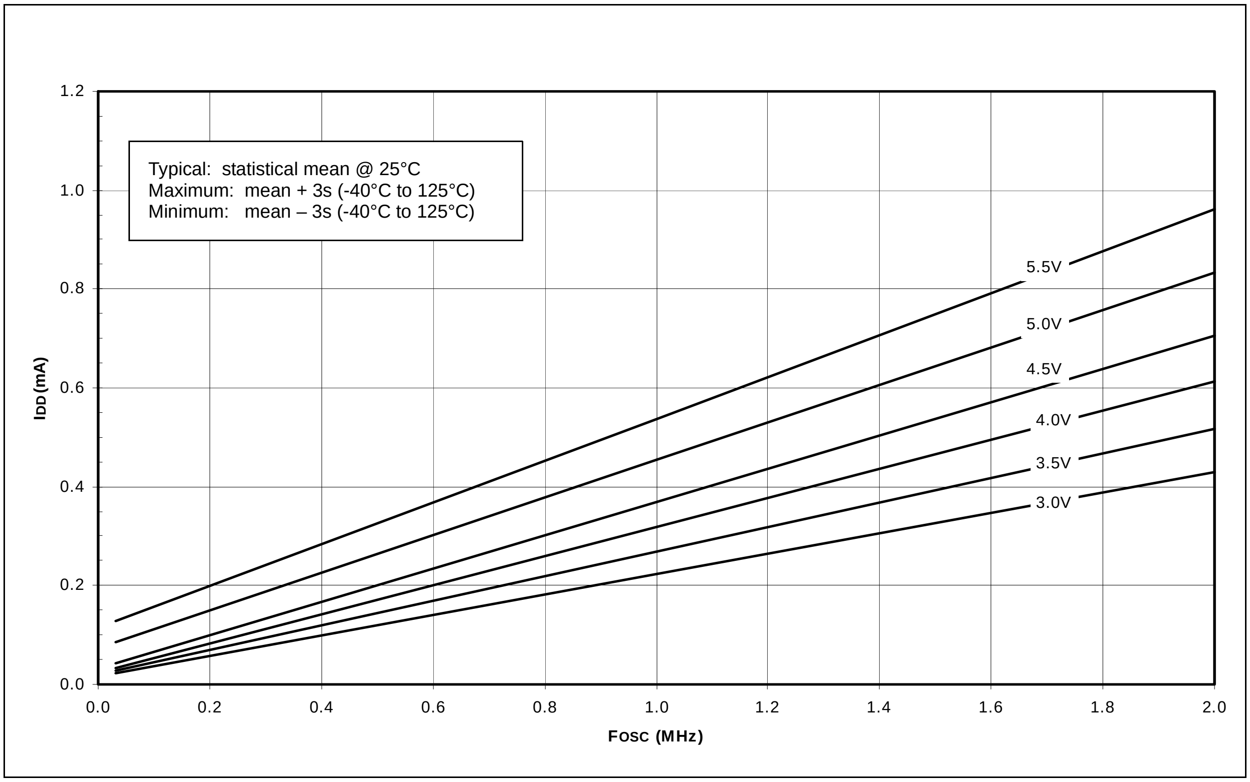
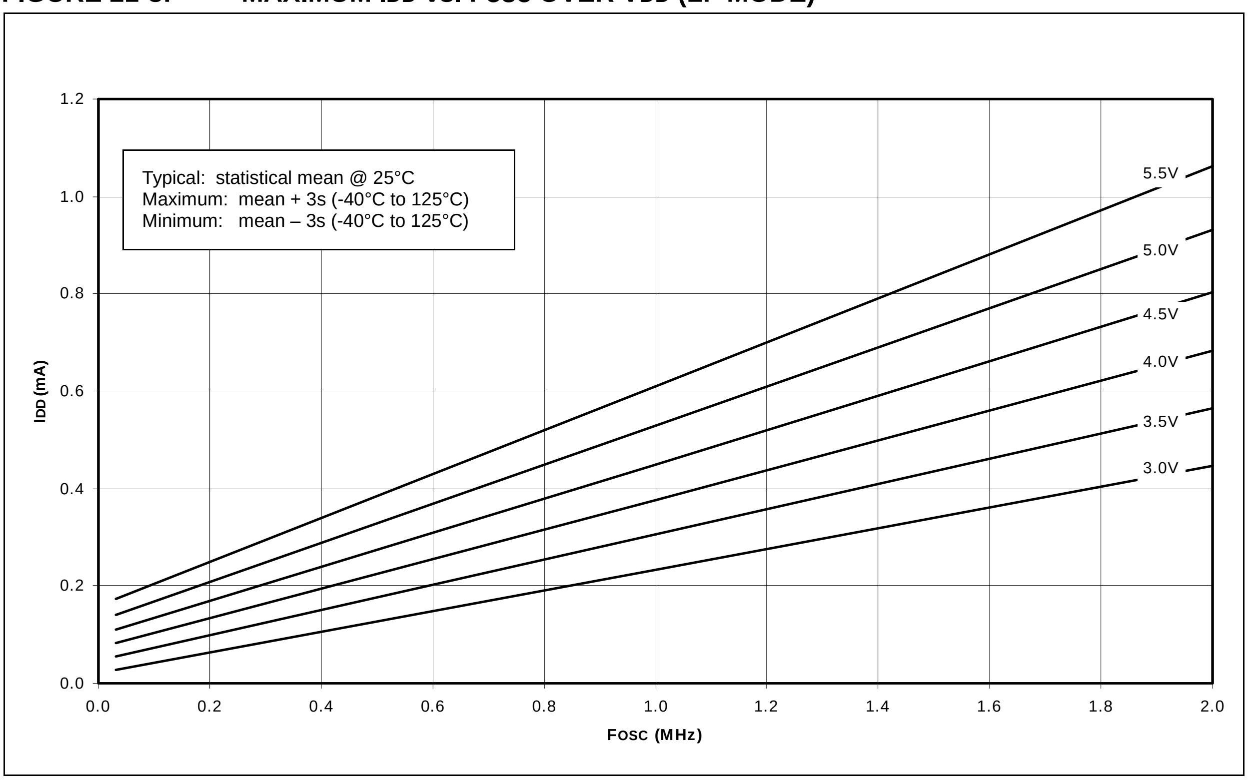


FIGURE 21-8: MAXIMUM IDD vs. FOSC OVER VDD (LF MODE)



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